
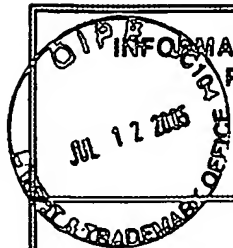


INFORMATION DISCLOSURE STATEMENT  PEO-1449 (PAGE 1 OF 1)	SERIAL NUMBER 10/766,564	DOCKET NO. P57001
	APPLICANT TAE-SUNG KIM	
	FILING DATE 29 January 2004	GROUP 2826

U.S. PATENT DOCUMENTS							
EXAMINER	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RZ	6,414,738	07/02	Fujikawa				
9	5,747,879	05/98	Rastogi, et al.				
B	6,255,706	07/01	Watanabe, et al.				
R	2001/0043175	11/01	Yasukawa				
h	2002/0076574	06/02	Cabral, Jr., et al.				
R	2002/0085157	07/02	Tanaka, et al.				
FOREIGN PATENT DOCUMENTS						TRANSLATION	
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO
R	EP 1 011 463	05/00	EUROPE			Abstract	
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
	European Office Action of the European Patent Application No. 04250453.0, mailed on 30 January 2006						
RO	An article "Relationship between copper concentration and stress during electromigration in an Al(0.25 at. % Cu) conductor line" written by Kao, et al. published in Journal of Applied Physics, Vol. 93, no. 5, pp 2516-2527, on 1 March 2003.						
RE	An article "The microstructure of submicrometer wide planar-reactive ion etched versus trench-damascene AlCu lines: written by Rodbell, et al., published in Journal of Applied Physics, Vol. 88, no. 9, pp 5093-5099, on 1 November 2000.						
RB	An article "Stress Induced Metallurgical Effects in Ti/TiN/AlCu/TiN Metal Stacks" written by Koller, et al., published in Stress Induced Phenomena in Metallization, Vol. 612, pp 235-246, on April 2002.						
EXAMINER:	Jill Pambert			DATE CONSIDERED: 05/25/06			
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INFORMATION DISCLOSURE STATEMENT
PTO-1449 (PAGE 1 OF 2)

SERIAL NUMBER 10/766,564

DOCKET NO. P57001

APPLICANT

TAE-SUNG KIM

FILING DATE 29 January 2004

GROUP 2826

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P	6,448,612	9/02	Miyazaki et al.			
	6,440,752	8/02	Zhang et al.			
	6,348,735	2/02	Yamaoka et al.			
	6,147,375	11/00	Yamazaki et al.			
	5,555,112	9/96	Oritsuki et al.			
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	5,345,108	9/94	Kikkawa			
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	4,153,529	5/79	Little et al.			
	6,147,403	11/00	Matschitsch et al.			
	6,166,396	12/00	Yamazaki			
	4,782,380	11/88	Shankar et al.			
	6,285,123	9/01	Yamada et al.			
✓	5,742,468	4/98	Matsumoto et al.			

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TRANSLATION

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO
P	JP09-153623	6/97	Japan			Abstract	
	JP09-45927	2/97	Japan			Abstract	
✓	JP04-265757	9/92	Japan			Abstract	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

EXAMINER:

[Signature]

DATE CONSIDERED:

05/25/06

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